

ABSTRACT

An apparatus for electropolishing a conductive material layer is disclosed. The apparatus comprises a porous conductive member configured to contact the conductive layer and having a first connector for receiving electrical power, an electrode insulatively coupled to the porous conductive member having a second connector configured to receive electrical power, a holder insulatively coupled to the porous conductive member and the electrode configured to establish relative motion between the porous conductive member and the conductive layer, and a power supply coupled to the first connector and the second connector configured to supply the electrical power between the electrode and the porous conductive member for electropolishing the conductive layer.